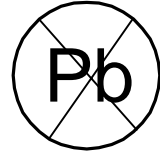




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BAR DIGIT LED DISPLAY



Lead-Free Parts

LBD141/2A-XX/S2

DATA SHEET

DOC. NO : QW0905-LBD141/2A-XX/S2

REV. : A

DATE : 11 - Feb. - 2009





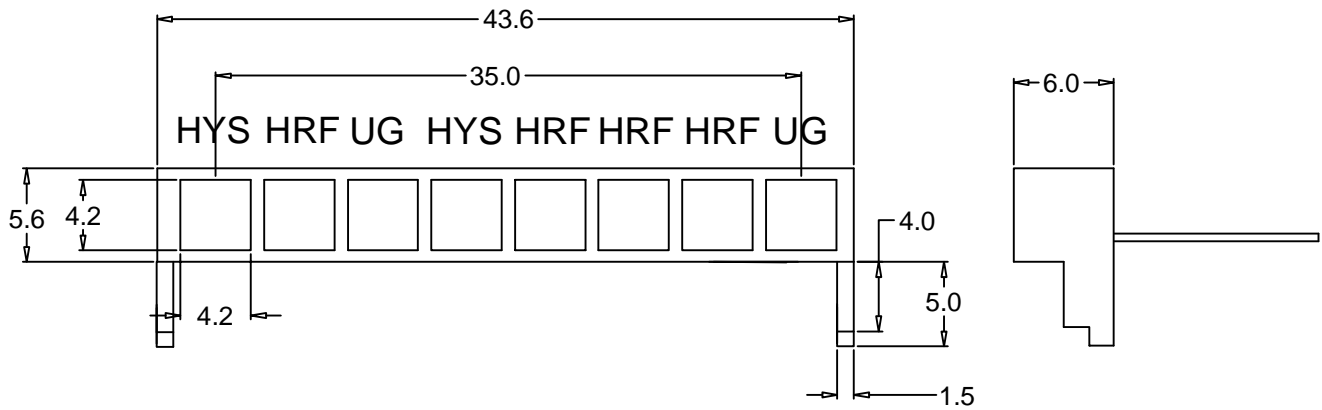
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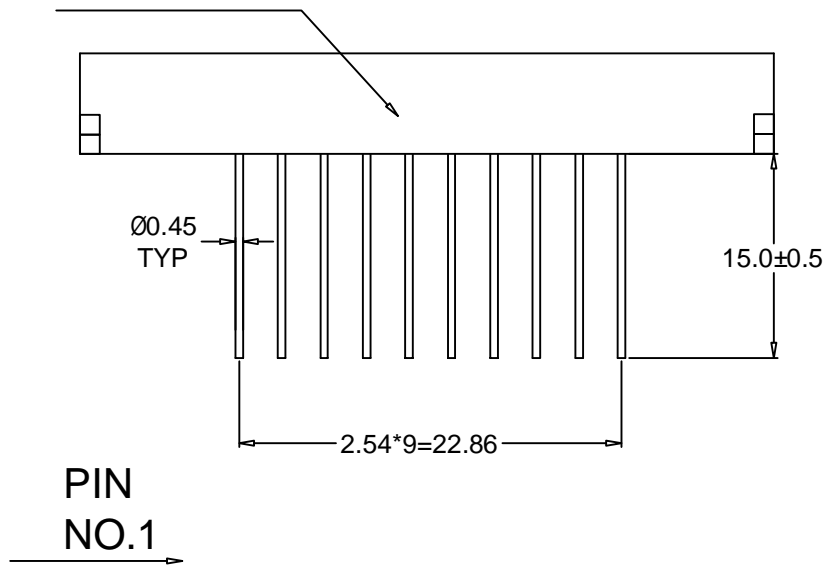
PART NO. LBD141/2A-XX/S2

Page 1/10

Package Dimensions



LBD141/2A-XX/S2
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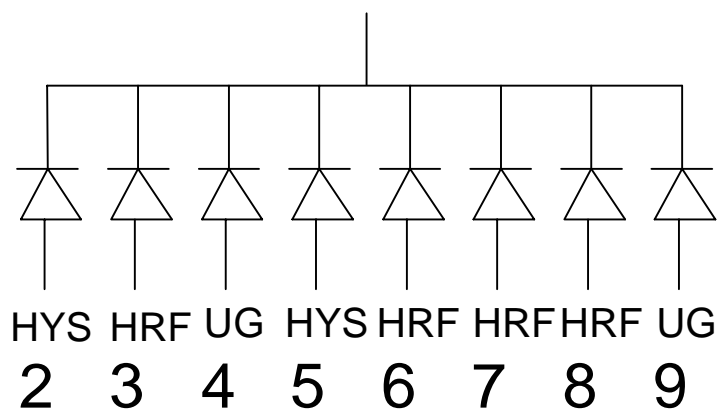
Note : 1.All dimension are in millimeters and (Inch) tolerance is ± 0.25 mm unless otherwise noted.
2.Specifications are subject to change without notice.



Internal Circuit Diagram

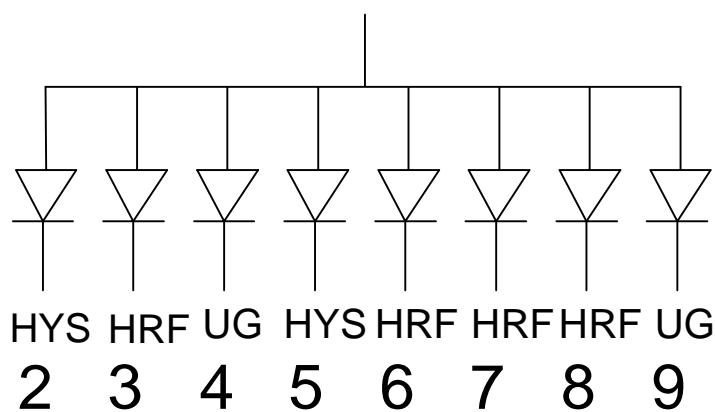
LBD141A-XX/S2

1, 10



LBD142A-XX/S2

1, 10





Electrical Connection

PIN NO.1	LBD141A-XX/S2	PIN NO.1	LBD142A-XX/S2
1	Common Cathode	1	Common Anode
2	Anode Yellow	2	Cathode Yellow
3	Anode Red	3	Cathode Red
4	Anode Green	4	Cathode Green
5	Anode Yellow	5	Cathode Yellow
6	Anode Red	6	Cathode Red
7	Anode Red	7	Cathode Red
8	Anode Red	8	Cathode Red
9	Anode Green	9	Cathode Green
10	Common Cathode	10	Common Anode



Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Ratings			UNIT
		HYS	HRF	UG	
Forward Current Per Chip	IF	30	30	30	mA
Peak Forward Current PerChip (Duty 1/10,0.1ms Pulse Width)	IFP	60	90	120	mA
Power Dissipation Per Chip	PD	75	75	100	mW
Reverse Current Per Any Chip	Ir	10			μA
Electrostatic Discharge	ESD	2000			μA
Operating Temperature	Topr	-40 ~ +85			°C
Storage Temperature	Tstg	-40 ~ +85			°C

Part Selection And Application Information(Ratings at 25°C)

PART NO	CHIP		common cathode or anode	λ D (nm)	Δ λ (nm)	Electrical					IV-M
	Material	Emitted				Vf(v)			Iv(mcd)		
						Min.	Typ.	Max.	Min.	Typ.	
LBD141A-XX/S2	AlGaInP	Yellow	Common Cathode	587	15	1.7	2.1	2.6	15.25	26	2:1
	AlGaInP	Red		630	20	1.5	1.7	2.4	6.1	10.5	2:1
LBD142A-XX/S2	AlGaInP	Green	Common Anode	574	20	1.7	2.1	2.6	10.5	18	2:1

Note : 1.The forward voltage data did not including ±0.1V testing tolerance.
2. The luminous intensity data did not including ±15% testing tolerance.

**Test Condition For Each Parameter**

Parameter	Symbol	Unit	Test Condition
Forward Voltage Per Chip	V _f	volt	I _f =20mA
Luminous Intensity Red Chip	I _v	mcd	I _f =30mA
Luminous Intensity Yellow or Green Chip	I _v	mcd	I _f =40mA
Dominant Wavelength	λ_D	nm	I _f =20mA
Spectral Line Half-Width	$\Delta\lambda$	nm	I _f =20mA
Reverse Current Any Chip	I _r	μA	V _r =5V
Luminous Intensity Matching Ratio	IV-M		



Typical Electro-Optical Characteristics Curve HYS CHIP

Fig.1 Forward current vs. Forward Voltage

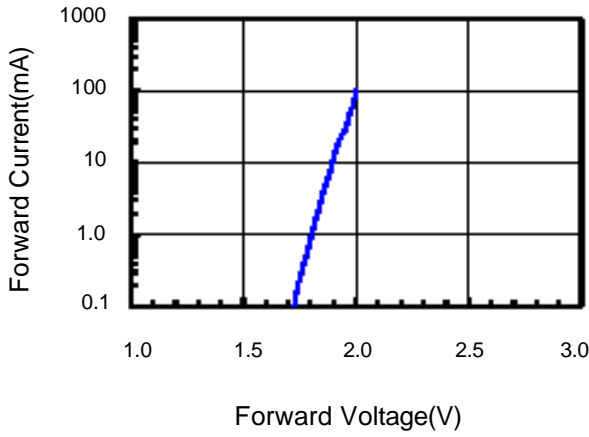


Fig.2 Relative Intensity vs. Forward Current

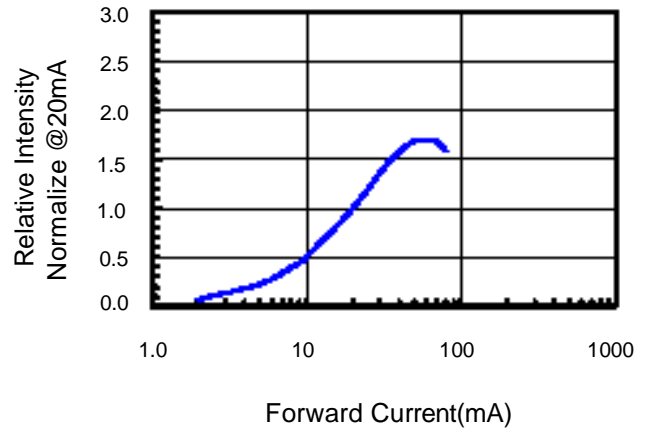


Fig.3 Forward Voltage vs. Temperature

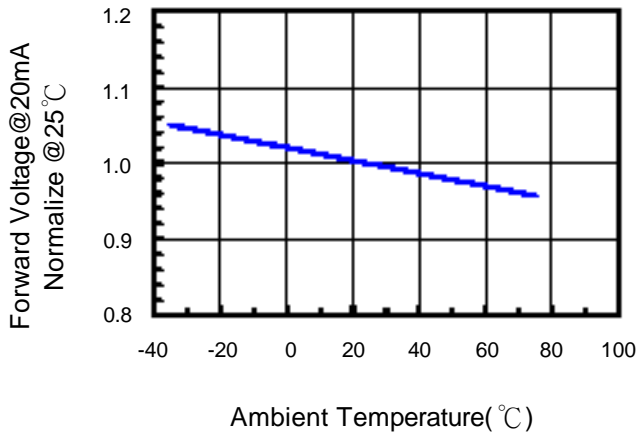


Fig.4 Relative Intensity vs. Temperature

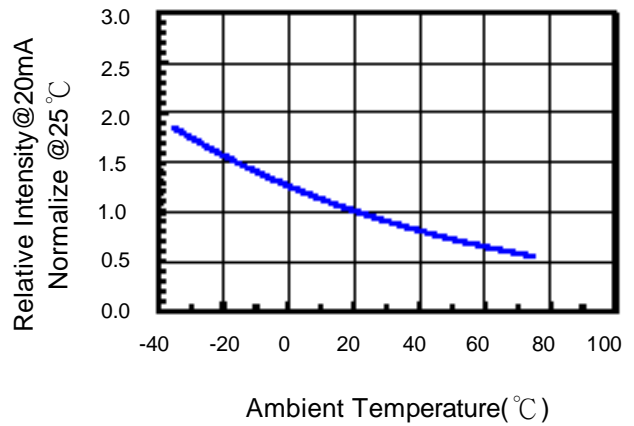
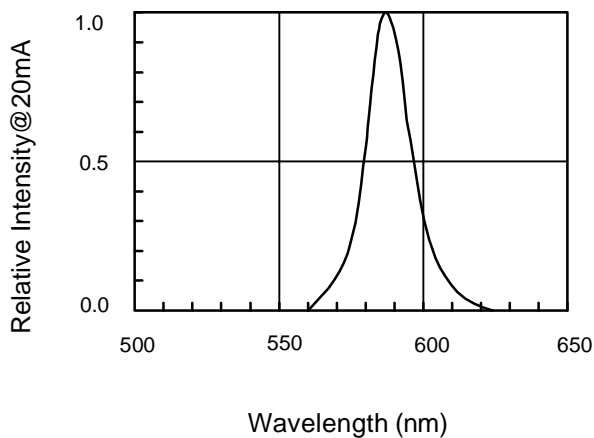


Fig.5 Relative Intensity vs. Wavelength





Typical Electro-Optical Characteristics Curve

HRF CHIP

Fig.1 Forward current vs. Forward Voltage

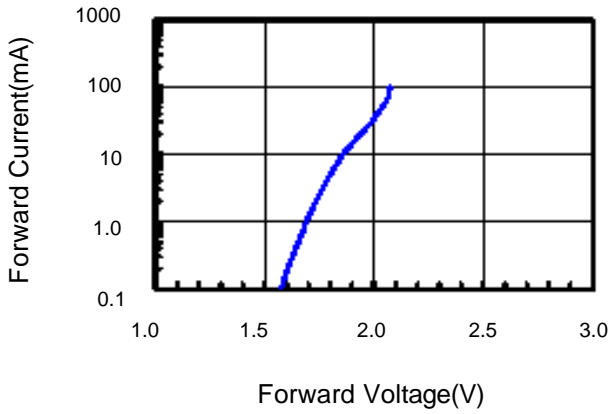


Fig.2 Relative Intensity vs. Forward Current

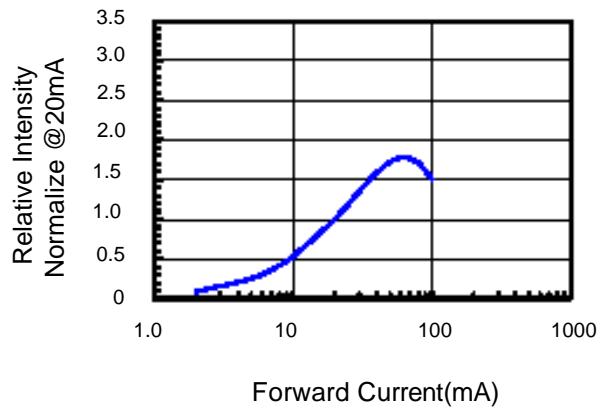


Fig.3 Forward Voltage vs. Temperature

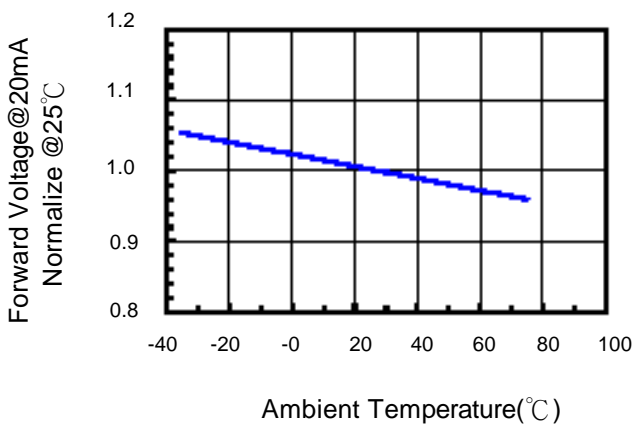


Fig.4 Relative Intensity vs. Temperature

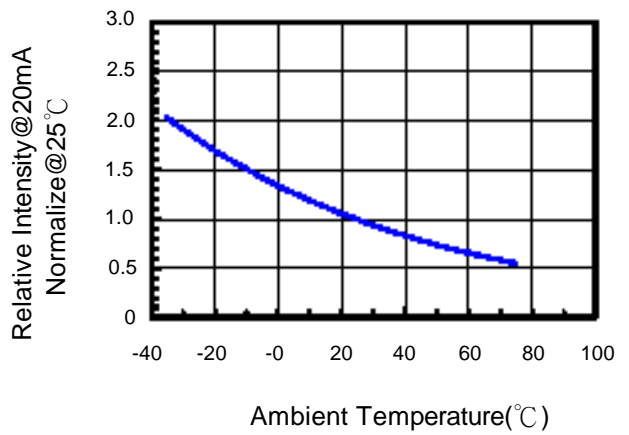
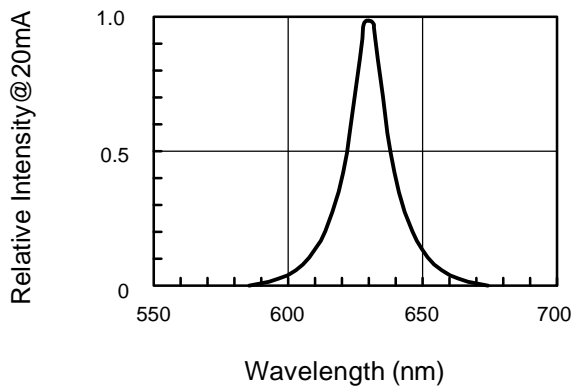


Fig.5 Relative Intensity vs. Wavelength





Typical Electro-Optical Characteristics Curve

UG CHIP

Fig.1 Forward current vs. Forward Voltage

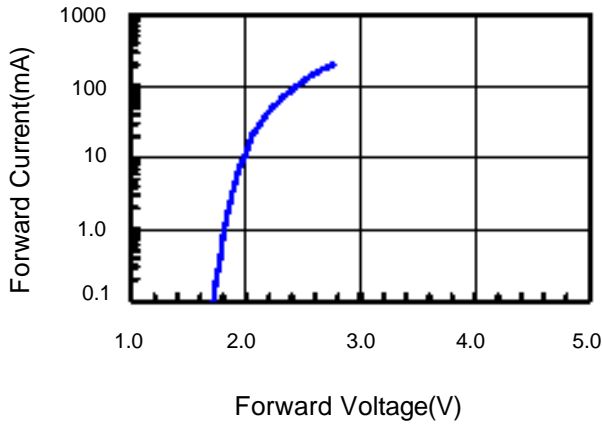


Fig.2 Relative Intensity vs. Forward Current

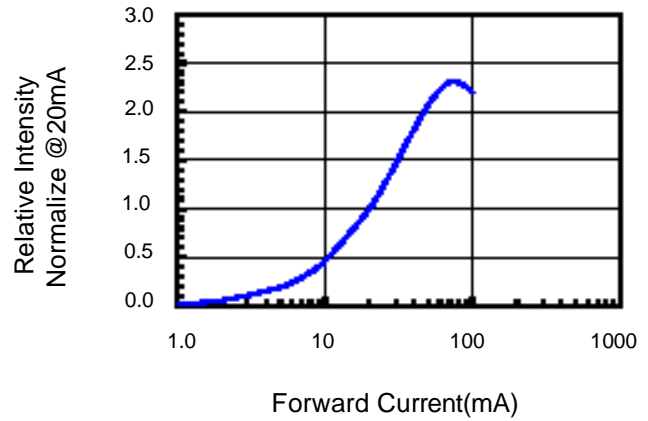


Fig.3 Forward Voltage vs. Temperature

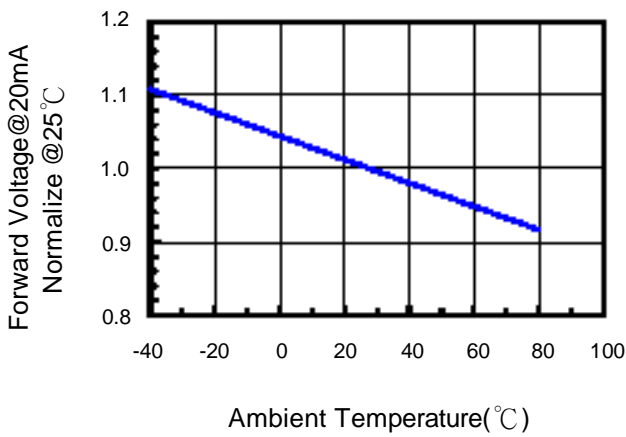


Fig.4 Relative Intensity vs. Temperature

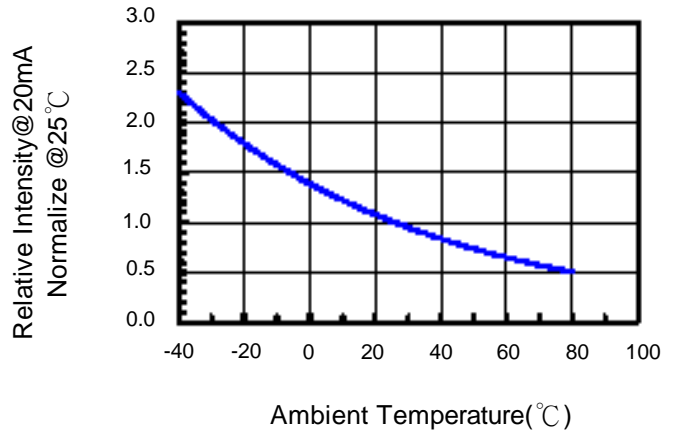
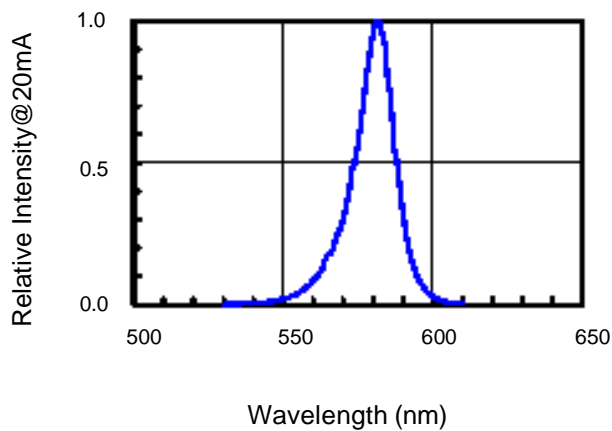


Fig.5 Relative Intensity vs. Wavelength





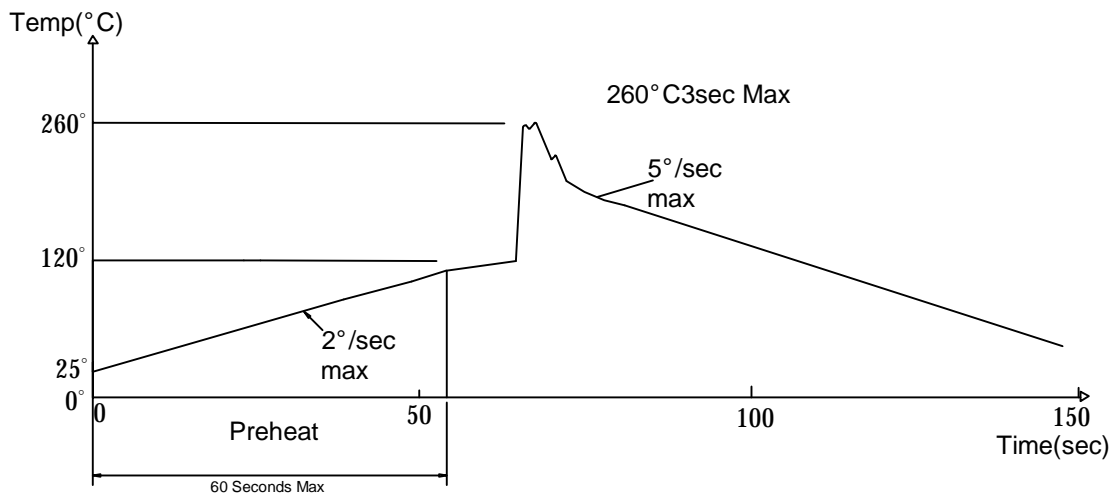
Soldering Condition(Pb-Free)

1.Iron:

Soldering Iron:30W Max
Temperature 350 ° C Max
Soldering Time:3 Seconds Max(One time only)
Distance:Solder Temperature 1/16 Inch Below Seating
Plane For 3 Seconds At 260 ° C

2.Wave Soldering Profile

Dip Soldering
Preheat: 120 ° C Max
Preheat time: 60seconds Max
Ramp-up
2 ° C/sec(max)
Ramp-Down:-5 ° C/sec(max)
Solder Bath:260 ° C Max
Dipping Time:3 seconds Max
Distance:Solder Temperature 1/16 Inch Below Seating
Plane For 3 Seconds At 260 ° C



Note: 1.Wave solder should not be made more than one time.
2.You can just only select one of the soldering conditions as above.

**Reliability Test:**

Test Item	Test Condition	Description	Reference Standard
Operating Life Test	1.Under Room Temperature 2.If=10mA 3.t=1000 hrs (-24hrs, +72hrs)	This test is conducted for the purpose of determining the resistance of a part in electrical and thermal stressed.	MIL-STD-750: 1026 MIL-STD-883: 1005 JIS C 7021: B-1
High Temperature Storage Test	1.Ta=105°C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of high temperature for hours.	MIL-STD-883:1008 JIS C 7021: B-10
Low Temperature Storage Test	1.Ta=-40°C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	The purpose of this is the resistance of the device which is laid under condition of low temperature for hours.	JIS C 7021: B-12
High Temperature High Humidity Test	1.Ta=65°C±5°C 2.RH=90%~95% 3.t=240hrs±2hrs	The purpose of this test is the resistance of the device under tropical for hours.	MIL-STD-202:103B JIS C 7021: B-11
Thermal Shock Test	1.Ta=105°C±5°C & -40°C±5°C (10min) (10min) 2.total 10 cycles	The purpose of this is the resistance of the device to sudden extreme changes in high and low temperature.	MIL-STD-202: 107D MIL-STD-750: 1051 MIL-STD-883: 1011
Solder Resistance Test	1.T.Sol=260°C±5°C 2.Dwell time= 10±1sec.	This test intended to determine the thermal characteristic resistance of the device to sudden exposures at extreme changes in temperature when soldering the lead wire.	MIL-STD-202: 210A MIL-STD-750: 2031 JIS C 7021: A-1
Solderability Test	1.T.Sol=230°C±5°C 2.Dwell time=5±1sec	This test intended to see soldering well performed or not.	MIL-STD-202: 208D MIL-STD-750: 2026 MIL-STD-883: 2003 JIS C 7021: A-2